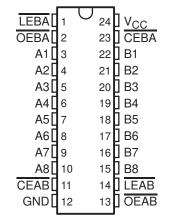
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce)
 1 V at V_{CC} = 5 V, T_Δ = 25°C
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

description

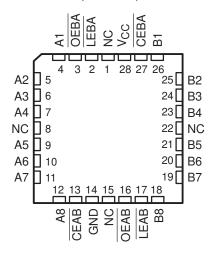
The 'ABT543 octal transceivers contain two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable (CEAB) input must be low in order to enter data from A or to output data from B. If CEAB is low and LEAB is low, the A-to-B latches are transparent; a subsequent low-to-high transition of LEAB puts the A latches in the storage mode. With CEAB and OEAB both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the CEBA, LEBA, and OEBA inputs.

SN54ABT543 . . . JT PACKAGE SN74ABT543 . . . DB, DW, OR NT PACKAGE (TOP VIEW)



SN54ABT543 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT543 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54ABT543 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT543 is characterized for operation from –40°C to 85°C.

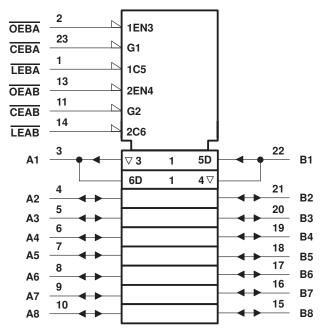
EPIC-IIB is a trademark of Texas Instruments Incorporated

FUNCTION TABLE†

	INPL	OUTPUT		
CEAB	LEAB	OEAB	Α	В
Н	Χ	Х	Χ	Z
Х	Χ	Н	Χ	Z
L	Н	L	Χ	в ₀ ‡
L	L	L	L	L
L	L	L	Н	Н

[†]A-to-B data flow is shown; B-to-A flow control is the same except that it uses $\overline{\mathsf{CEBA}}$, $\overline{\mathsf{LEBA}}$, and $\overline{\mathsf{OEBA}}$.

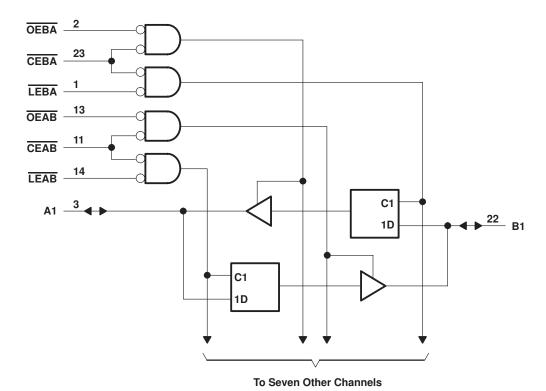
logic symbol§



 $\$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, and NT packages.

[‡]Output level before the indicated steady-state input conditions were established.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to	7 V כ
Input voltage range, V _I (except I/O ports) (see Note 1)	–0.5 V to	ว 7 V
Voltage range applied to any output in the high state or power-or	off state, V_O -0.5 V to 5	5.5 V
Current into any output in the low state, IO: SN54ABT543		Am 6
SN74ABT543		3 mA
Input clamp current, I _{IK} (V _I < 0)		3 mA
Output clamp current, I _{OK} (V _O < 0)) mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 2	2): DB package 0.6	35 W
	DW package 1.	.7 W
	NT package	.3 W
Storage temperature range	–65°C to 1	50°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



^{2.} The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the NT package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

SN54ABT543, SN74ABT543 OCTAL REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS157A - JANUARY 1991 - REVISED JULY 1994

recommended operating conditions (see Note 3)

			SN54A	BT543	SN74A		
			MIN	MAX	MIN	MAX	UNIT
VCC	V _{CC} Supply voltage				4.5	5.5	V
V _{IH}	V _{IH} High-level input voltage				2		V
V _{IL}	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0 4	V _{CC}	0	VCC	V
lOH	High-level output current		Ç	-24		-32	mA
lOL	Low-level output current		200	48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	120	5		5	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS			Т	A = 25°C	;	SN54A	BT543	SN74ABT543			
PARAMETER				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK	$V_{CC} = 4.5 \text{ V}, \qquad I_{I} = -18 \text{ mA}$					-1.2		-1.2		-1.2	V	
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$		2.5			2.5		2.5		.,	
	V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$		3			3		3			
V _{OH}	V 45V	$I_{OH} = -24 \text{ m/s}$	١	2			2				V	
	V _{CC} = 4.5 V	I _{OH} = -32 mA		2*					2			
V	V 45V	$I_{OL} = 48 \text{ mA}$				0.55		0.55			٧	
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 64 mA				0.55*		Z.		0.55	V	
1.	$V_{CC} = 5.5 \text{ V},$		Control inputs			±1		S±1		±1	^	
lį .	$V_I = V_{CC}$ or GND		A or B ports			±100		±100		±100	μΑ	
I _{OZH} ‡	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$				10§	6	10§		10§	μΑ	
l _{OZL} ‡	$V_{CC} = 5.5 \text{ V}, \qquad V_{O} = 0.5 \text{ V}$					-10§	3	-10§		-10§	μΑ	
l _{off}	$V_{CC} = 0$,	$V_{CC} = 0$, $V_I \text{ or } V_O \le 4.5 \text{ V}$				±100	0			±100	μΑ	
ICEX	$V_{CC} = 5.5 V$,	$V_0 = 5.5 \text{ V}$	Outputs high			50	Q.	50		50	μΑ	
IO¶	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.5 \text{ V}$		-50	-100	-180	-50	-180	-50	-180	mA	
	V _{CC} = 5.5 V,		Outputs high		1	250		250		250	μΑ	
ICC	$I_{O} = 0$,	A or B ports	Outputs low		24	34§		34§		34§	mA	
	$V_I = V_{CC}$ or GND		Outputs disabled		0.5	250		250		250	μΑ	
ΔlCC [#]	$V_{CC} = 5.5 \text{ V},$ Other inputs at V_{CC}	3.4 V,			1.5		1.5		1.5	mA		
Ci	V _I = 2.5 V or 0.5 V		Control inputs		4						pF	
C _{io}	V _O = 2.5 V or 0.5 V		A or B ports		7						pF	

 $[\]ensuremath{^{\star}}$ On products compliant to MIL-STD-883, Class B, this parameter does not apply.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡]The parameters IOZH and IOZL include the input leakage current.

[§] This data sheet limit may vary among suppliers.

[¶]Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $^{^{\#}}$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V CC or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

					V _{CC} = 5 V, T _A = 25°C		SN54ABT543		SN74ABT543	
				MIN	MAX	MIN	MAX	MIN	MAX	
t _W Pulse duration, LEAB or LEBA low				3.5		3.5	Z.	3.5		ns
		Data before CEAB or CEBA↑	High	3.5		3.5	, N	3.5		ns
١.	Catura tima		Low	3		3	D.	3		
t _{su}	Setup time		High	3.5		3.5		3.5		
		Data before GEAB or GEBA	Low	3		3		3		
t. Hold !	Hold time	Data after LEAB or LEBA↑		1†		؆		1†		ns
^t h	Hold time	Data after CEAB or CEBA↑		1†		Q 1†		1†		110

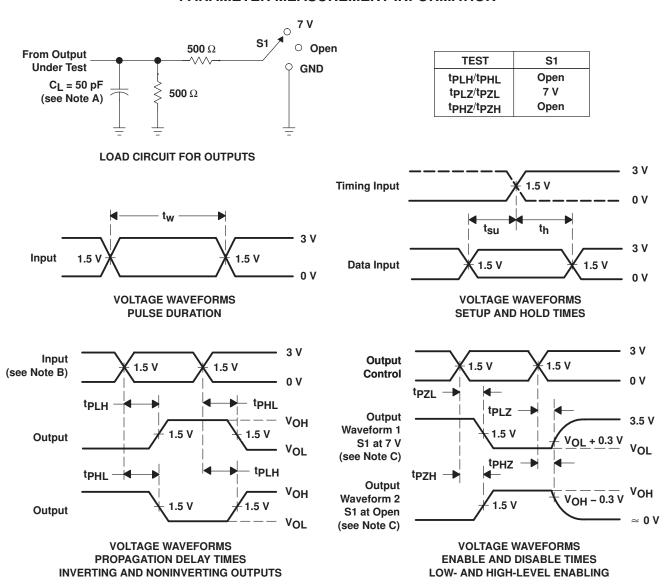
[†] This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT543		SN74ABT543		UNIT
	(INPUT)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A == D	D on A	1.9	4.4	5.9	1.9		1.9	6.9	
[†] PHL	A or B	B or A	1.9	4.4	5.9	1.9		1.9	6.9	ns
^t PLH	LEBA or LEAB	A or B	1.6	4.1	5.6	1.6	i, d	1.6	6.6	ns
^t PHL			2.1	4.6	6.1	2.1	Z	2.1	7.1	
^t PZH	0500	A or B	1.4	3.9	5.4	1.4	27	1.4	6.4	ns
^t PZL	OEBA or OEAB		2.5	5	6.5	2.5		2.5	7.5	
^t PHZ	OFDA OFAD		2.5†	5.9	7.4	2.51		2.5†	8.4	
^t PLZ	OEBA or OEAB	A or B	3	5.5	7	3		3	8	ns
^t PZH	CEBA or CEAB	CEAB A or B	1.4	3.9	5.4	1.4		1.4	6.4	
t _{PZL}			2.5	5	6.5	2.5		2.5	7.5	ns
^t PHZ	CEBA or CEAB	A D	3.2†	5.9	7.4	3.2†		3.2†	8.4	20
^t PLZ		A or B	3	5.5	7	3		3	8	ns

[†]This data sheet limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Applications Products Amplifiers amplifier.ti.com Audio www.ti.com/audio Data Converters Automotive dataconverter.ti.com www.ti.com/automotive **DLP® Products** Broadband www.dlp.com www.ti.com/broadband DSP Digital Control dsp.ti.com www.ti.com/digitalcontrol Clocks and Timers www.ti.com/clocks Medical www.ti.com/medical Interface Military www.ti.com/military interface.ti.com Optical Networking Logic logic.ti.com www.ti.com/opticalnetwork Power Mgmt power.ti.com Security www.ti.com/security Telephony Microcontrollers microcontroller.ti.com www.ti.com/telephony www.ti-rfid.com Video & Imaging www.ti.com/video RF/IF and ZigBee® Solutions www.ti.com/lprf Wireless www.ti.com/wireless

> Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2009, Texas Instruments Incorporated